





PBR activities in Trento

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SPB_2 activities

- EUSO-SPB2:
 - Data analysis
- Mini-EUSO
 - mission control
 - ground flashes campaigns
 - analysis
- EUSO-TA
 - operations on site in Utah
 - analysis,
 - upgrades
- PBR
 - CC, FC, γ and X cameras, DAQ&DP, software, simulations
 - INFN-ASI agreements, MoUs
 - During the last months: common participation in the preparation of the response to ESA 2025 M8&F3 calls that resulted in the submission of the M-EUSO proposal

HUGE UNCERTAINTY DUE TO NASA BUDGET CUT But the collaboration will go on until they eventually stop us

We are here!

Italian team

People officially involved in the JEM-EUSO activities for 2024 (SPB2, Mini-EUSO, EUSO TA, PBR, etc):

- $51 \rightarrow 64$ people (30 FTE) + 25% since last year
 - 58 researchers
 - 6 technologists
- 9 Institutions
 - Bari (Resp. F. Cafagna): PBR mechanics and software
 - Catania (R. Caruso): CC modules test and calibration, analysis of SPB2 and Mini-EUSO data
 - Gran Sasso Science Institute (GSSI/LNGS) (A. Di Giovanni): NUSES mission
 - Lecce (V. Scherini): Simulations
 - Napoli (G. Osteria): PBR telescope DAQ and trigger, Cherenkov Camera, simulations, tests
 - Roma Tor Vergata (M. Casolino): Mini-EUSO, EUSO TA, PBR FC DAQ, PBR CC DAQ, PBR X-gamma
 - Trento (TIFPA) (E. Ricci): SiPM bias system for PBR Cherenkov camera
 - Torino (M. Bertaina): MIZAR ASIC development for PBR, analysis of SPB2 and Mini-EUSO data
 - Trieste (Resp. R. Munini): Simulation of PBR CC

PBR CC overview

Requirements (from simulations):

- Pixel size: 3 x 3 mm2
- Pixel FoV: 0.2°
- Total FoV: 12° x 6° Implementation:
- SiPM arrays:
 - 64 pixels (8 x 8)
 - 4 x 8 = 32 SiPM arrays
 - 2048 pixels
 - four CC-PDMs (1x8 SiPM arrays, 512 pixels)





- Each CC-PDM is connected to an ASIC board (two solutions under investigation)
- The ASIC board is connected to an FPGA board
- In the current design the SiPM bias system is hosted on the FPGA board
- The desing is not frozen yet



CC status



SiPM matrix: Hamamatsu S13361-3050AE-08 Procurement completed.

Assembly of elementary cells ongoing

40 elementary cells manufactured 30 FM quality



Readout solutions:

- Weeroc Radioroc
 - Board in production
 - More complex, lower performance
 - Off-the-shelf components
- MIZAR ASIC:
 - Developed by INFN-TO.
 - First batch arrived in April
 - Characterisation ongoing
 - No major issues spotted until now!!!

Bias system

To optimize the per formance of the SiPM matrices, each of them should **be powered independently** with a source that can **adapt with the temperature**

- Limited off-the-shelf solutions
- No devices with the required temperature range (-30° to +85°, industrial standard)
- Limited time, a custom solution is currently not viable
- Device selected: CAEN A7585
 - Not qualified in temperature
 - Big device (3x3 cm²). The space is limited on the board
- Component under test at TIFPA for temperature qualification (ongoing)
- Already integrated on the FPGA board design
- Due to limited space, we decided to use **one power supply for two SiPM matrices**





Ongoing tests

- We are using a version of the A7585 that can be read using USB port connected to an Arduino
- The setup is inside the climate chamber and thermal cycles are run on the setup
- The test started yesterday (29/6/2025) and are ongoing smoothly for now



People and requests

Under construction, we need to agree how to split the FTEs of people involved in connected projects

Person	Current position	FTE
E. Ricci (Loc. Resp)	RTDa UNITN	0.3
F. Acerbi	FBK	0.3
A. Ficorella	FBK	0.2
A. Gola	FBK	0.2
S. Merzi	FBK	0.3
G. Paternoster	FBK	0.2
TOTALE		1.5

Status spese 2025: Assegnato: 16 k Speso: 3k

Spesa	Richieste
Missioni (turni integrazione e test in USA, Europa e Italia)	10k
Consumabili (materiale per climate chamber, componenti per test di caratterizzazione materiale spare)	2k
TOTALE	12k

Le richieste di missione sono calibrate in accordo con la collaborazione in base ai test in cui la sezione è coinvolta.